

## Features

- SiC MOSFET Technology
- High Speed Switching
- Reduction Of Heat Sink Requirements
- Essentially No Switching Losses
- Halogen Free. "Green" Device <sup>(Note 1)</sup>
- Lead Free Finish/RoHS Compliant("P" Suffix Designates RoHS Compliant. See Ordering Information) <sup>(Note2)</sup>

## Maximum Ratings

- Operating Junction Temperature Range : -55°C to +175°C
- Storage Temperature Range: -55°C to +175°C
- Thermal Resistance Junction to Ambient,Max<sup>(Note 3)</sup>: 62°C/W
- Thermal Resistance Junction to Case,Typ : 0.90°C/W

## Applications

- Solar Inverters
- Uninterruptible Power Supply
- Photovoltaic Inverter
- Battery Chargers
- Motor Drives

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	1200	V
Gate-Source Voltage <sup>(Note 4)</sup>	V <sub>GSm</sub>	-10/+25	V
Gate-Source Voltage	V <sub>GSop</sub>	-5/+20	V
Continuous Drain Current V <sub>GS</sub> =20V	I <sub>D</sub>	24	A
Tc=110°C		16.5	
Pulsed Drain Current <sup>(Note 5)</sup>	I <sub>DM</sub>	65	A
Total Power Dissipation	P <sub>D</sub>	166	W
Tc=110°C		71	
Avalanche Energy, Single Pulse	E <sub>AS</sub>	625	mJ

Note1:Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

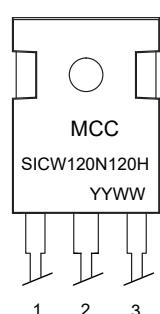
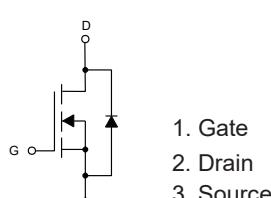
Note2:High Temperature Solder Exemptions Applied, see EU Directive Annex 7a.

Note3:Device in a still air environment with TA=25°C.

Note4:AC f > 1Hz, duty cycle < 1%

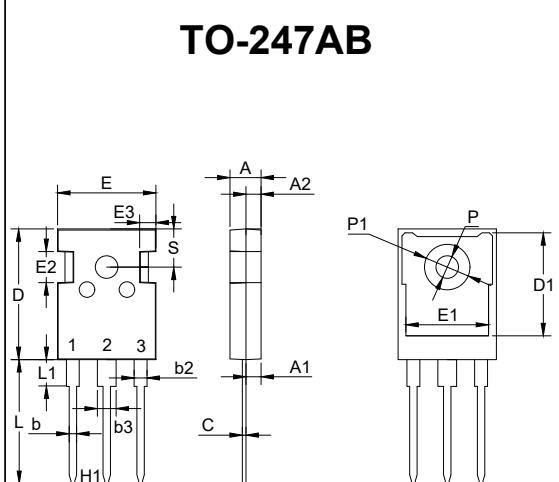
Note5:Pulse Test: Pulse Width Limited by Tjmax.

## Internal Structure and Marking Code



Device Code: SICW120N120H  
Date Code: YYWW (Year & Week)

# SiC N-CHANNEL MOSFET

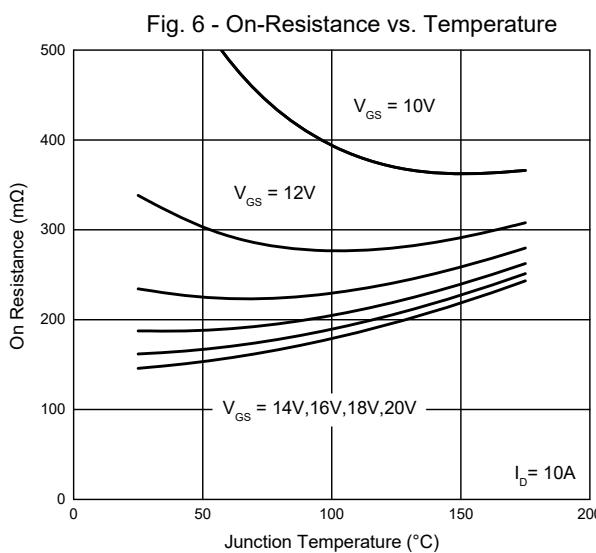
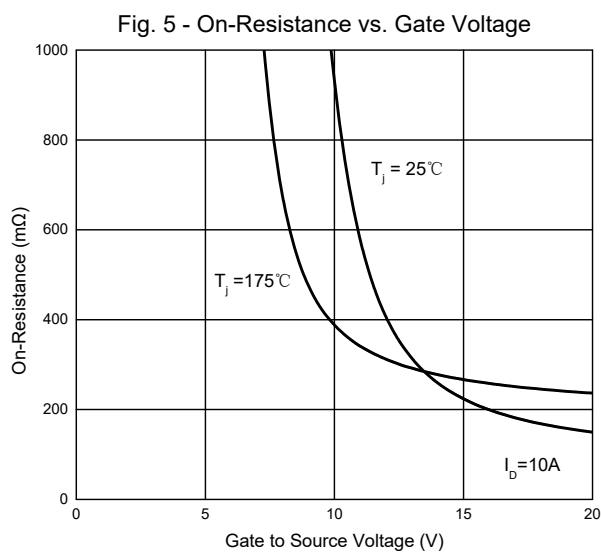
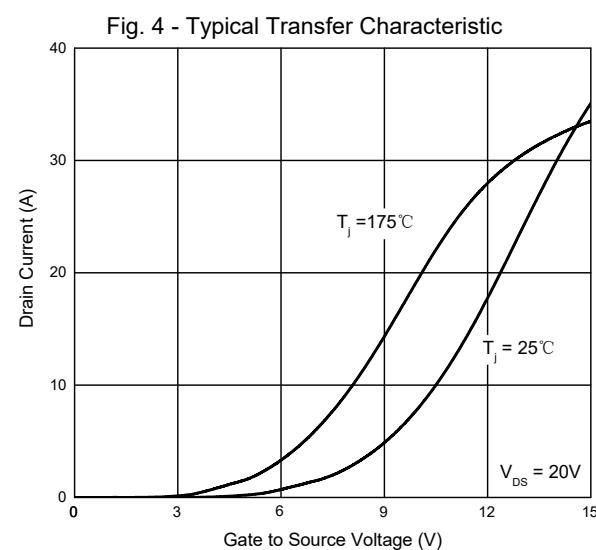
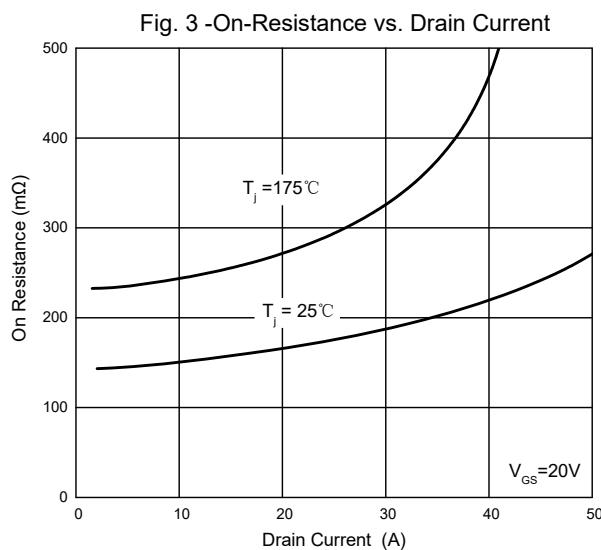
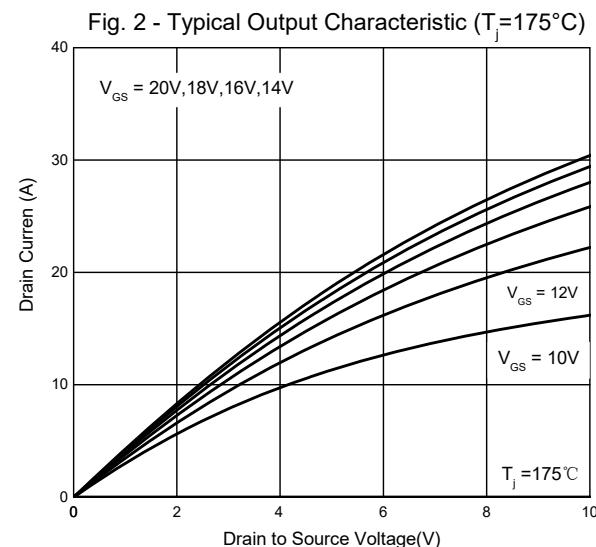
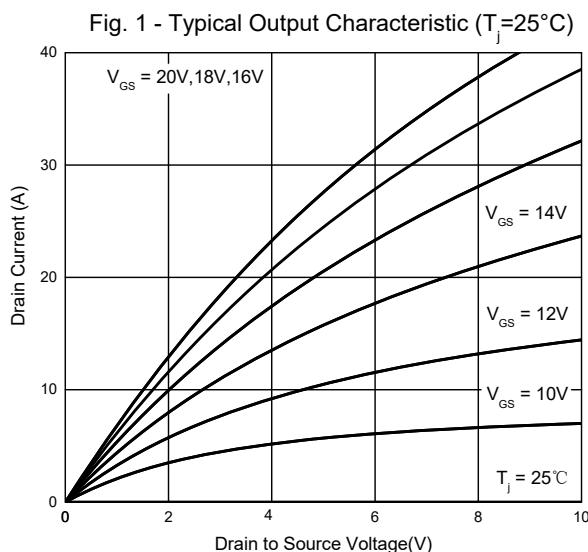


DIM	DIMENSIONS				NOTE
	INCHES	MIN	MAX	MM	
A	0.189	0.205	4.80	5.20	
A1	0.087	0.103	2.21	2.61	
A2	0.073	0.085	1.85	2.15	
b	0.039	0.055	1.00	1.40	
b2	0.075	0.087	1.91	2.21	
C	0.020	0.028	0.50	0.70	
D	0.815	0.839	20.70	21.30	
D1	0.640	0.663	16.25	16.85	
E	0.610	0.634	15.50	16.10	
E1	0.512	0.535	13.00	13.60	
E2	0.189	0.205	4.80	5.20	
E3	0.091	0.106	2.30	2.70	
L	0.772	0.796	19.62	20.22	
L1	-	0.177	-	4.50	
P	0.134	0.150	3.40	3.80	Φ
P1		0.287	-	7.30	Φ
S		0.242		6.15	TYP
H1		0.214		5.44	TYP
b3	0.110	0.126	2.80	3.20	

**Electrical Characteristics @  $T_j=25^\circ\text{C}$  (Unless Otherwise Specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS}=0\text{V}, I_D=100\mu\text{A}$	1200			V
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=20\text{V}$			250	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=1200\text{V}, V_{GS}=0\text{V}$			50	$\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=10\text{mA}$	2	2.95	4.5	V
Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS}=20\text{V}, I_D=10\text{A}$		120	160	$\text{m}\Omega$
		$V_{GS}=20\text{V}, I_D=10\text{A}, T_j=175^\circ\text{C}$		200		$\text{m}\Omega$
Internal Gate Resistance	$R_g$	$f=1\text{MHz}, V_{AC}=25\text{mV}$		1.8		$\Omega$
Transconductance	$g_{FS}$	$V_{DS}=12.5\text{V}, I_D=60\text{A}$		6.2		s
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=800\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}, V_{AC}=25\text{mV}$		1083		pF
Output Capacitance	$C_{oss}$			56		
Reverse Transfer Capacitance	$C_{rss}$			8		
Cross Stored Energy	$E_{oss}$			23		$\mu\text{J}$
Total Gate Charge	$Q_g$	$V_{DS}=800\text{V}, V_{GS}=-5/+20\text{V}, I_D=10\text{A}$		67		nC
Gate-Source Charge	$Q_{gs}$			14.5		
Gate-Drain Charge	$Q_{gd}$			29		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD}=800\text{V}, V_{GS}=0/+20\text{V}, R_G=10\Omega, I_D=8\text{A}, R_L=100\Omega$		24		ns
Rise Time	$t_r$			24		
Turn-Off Delay Time	$t_{d(\text{off})}$			34		
Fall Time	$t_f$			33		
Turn-On switching energy	$E_{on}$	$V_{DD}=800\text{V}, V_{GS}=0/+20\text{V}, R_G=2.7\Omega, I_D=10\text{A}$		13		$\mu\text{J}$
Turn-Off switching energy	$E_{off}$			19		
<b>Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$V_{GS}=0\text{V}, T_C=25^\circ\text{C}$		25		A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_{SD}=2.5\text{A}$		3.4		V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0\text{V}, I_{SD}=10\text{A}, V_{DS}=400\text{V}, dI_F/dt=300\text{A}/\mu\text{s}$		53		ns
Reverse Recovery Charge	$Q_{rr}$			63		nC
Peak Reverse Recovery Current	$I_{rrm}$			2.25		A

## Curve Characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified)



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Fig. 7 - Normalized On-Resistance vs. Temperature

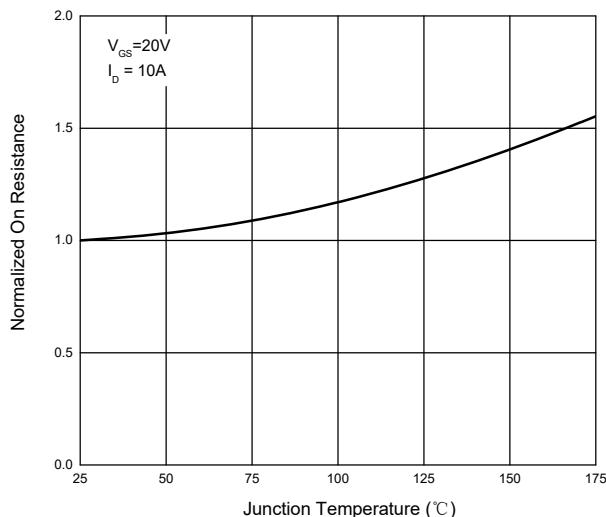


Fig. 8 - Reverse Output Voltage

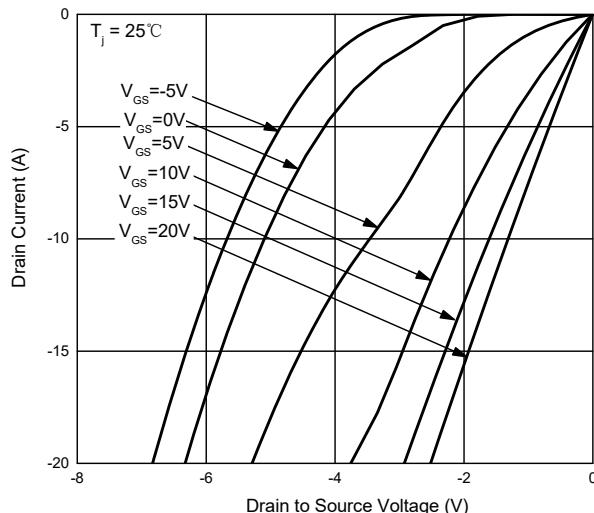


Fig. 9 - Reverse Output Voltage

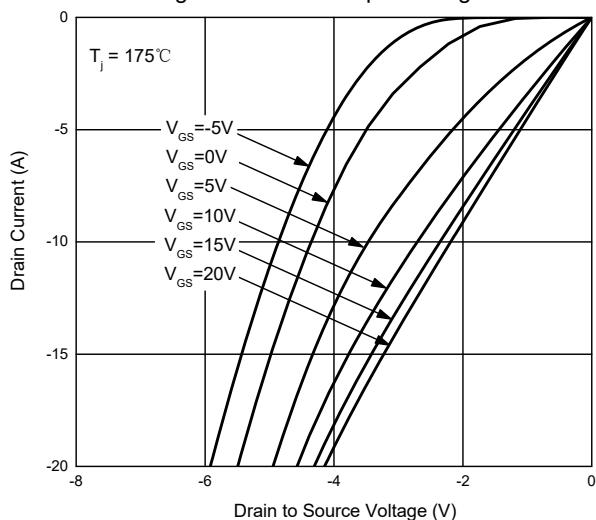


Fig. 10 - Capacitances vs.  $V_{DS}$

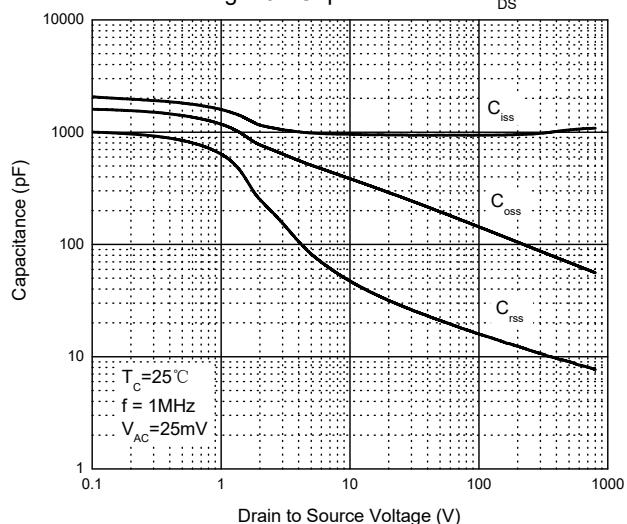


Fig. 11 - Threshold Voltage vs. Temperature

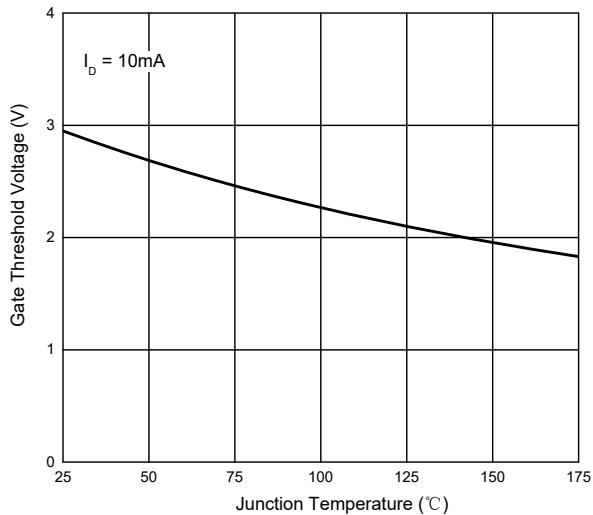
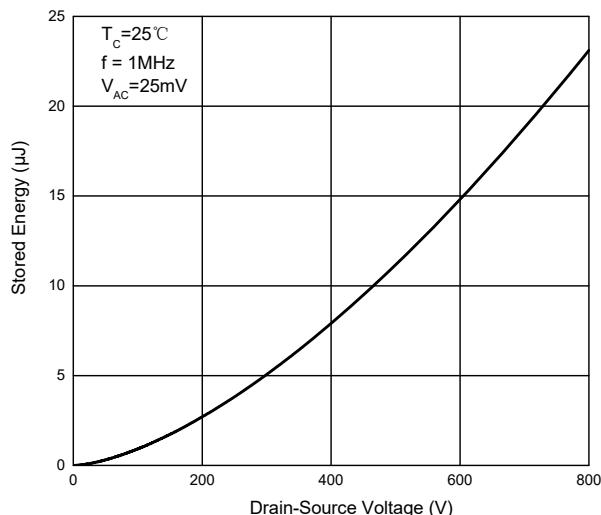


Fig. 12 - Output Capacitor Stored Energy



**Curve Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Fig. 13 - Power Derating

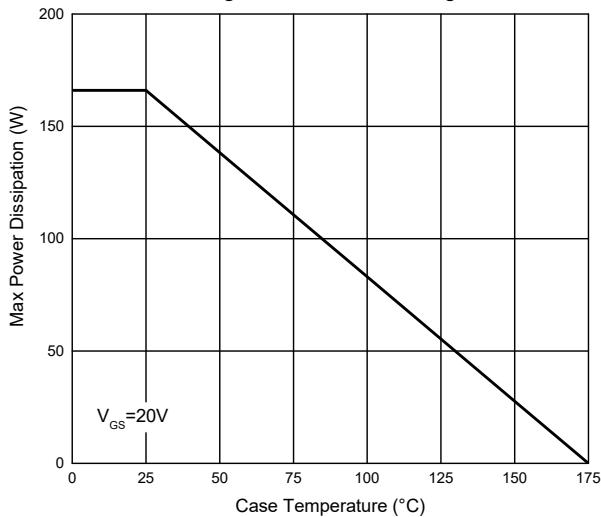


Fig. 14 - Drain Current Derating

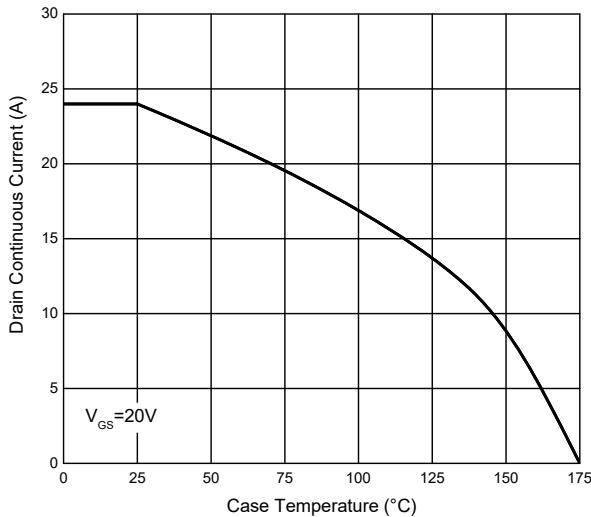


Fig. 15 - Safe Operation Area

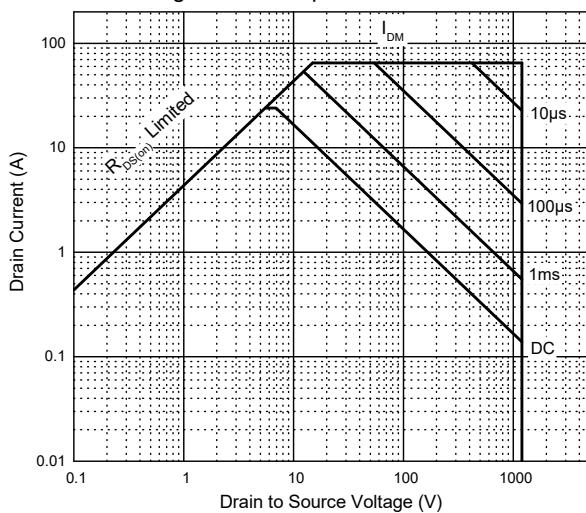


Fig. 16 - Typical Gate Charge

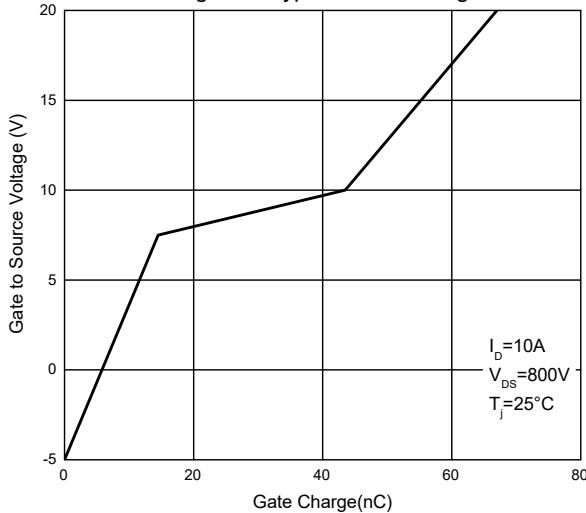


Fig. 17 - Clamped Inductive Switching Energy vs. Drain Current

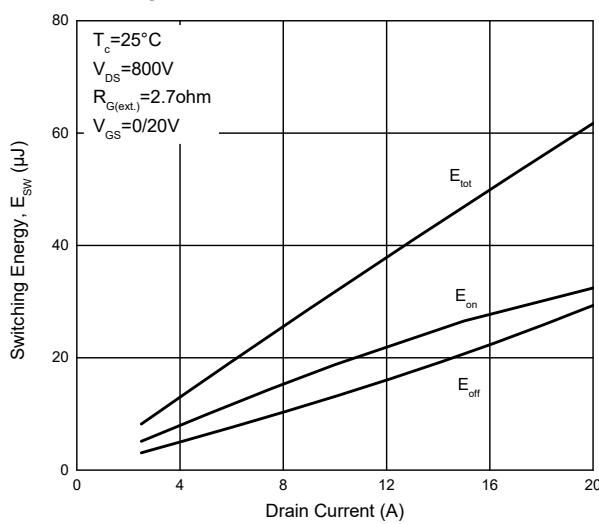
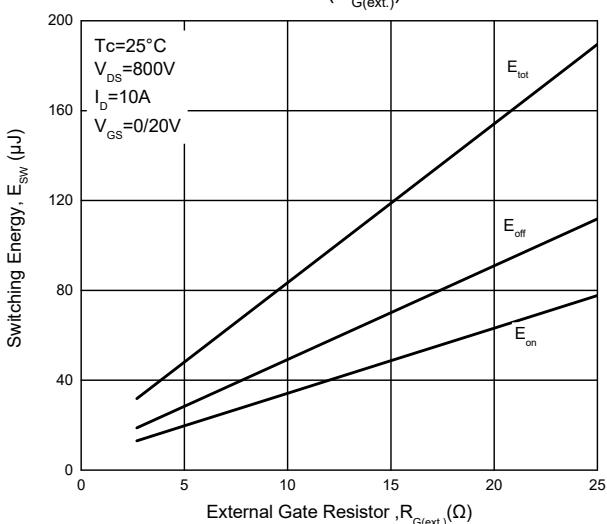
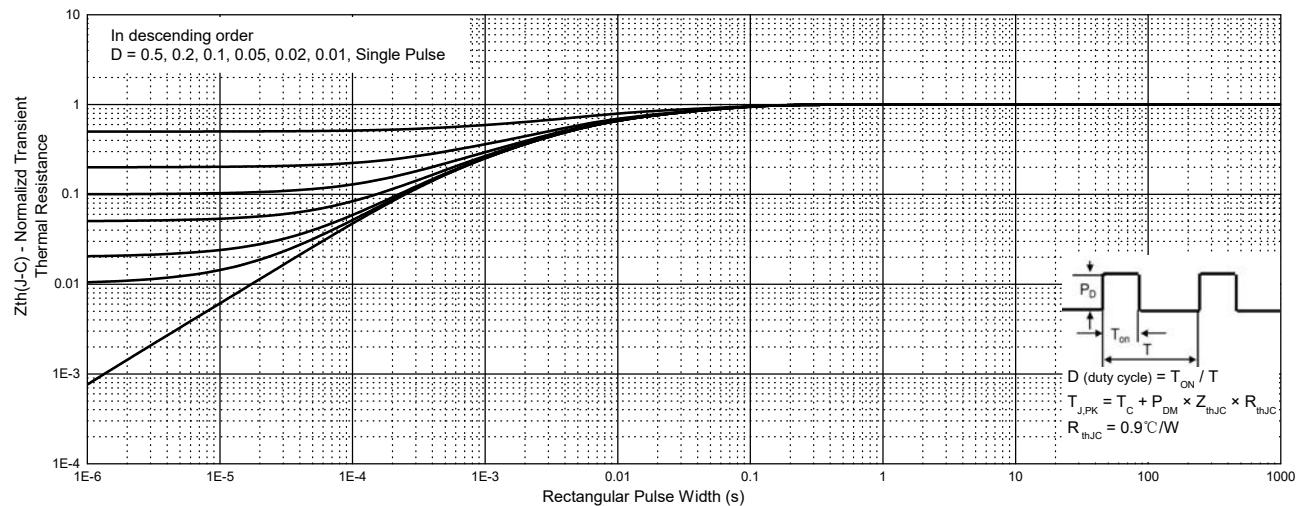


Fig. 18 - Clamped Inductive Switching Energy vs. External Gate Resistor ( $R_{G(ext.)}$ )



## Curve Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Fig.19 - Normalized Transient Thermal Impedance



## Ordering Information

Device	Packing
SICW120N120H-BP	Tube:30pcs/Tube, 1.8K/Ctn;

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